

ABSTRACT OF THE DISCLOSURE

A semiconductor manufacturing apparatus comprising an integrated measuring instrument for measuring the form or size of the element to be formed into a wafer, an etching unit for etching the wafer by making use of plasma generated under reduced pressure, an ashing unit for ashing the etched wafer, a wetting unit for wetting the etched wafer, a drying unit for drying the wafer which has gone through the wetting treatment, a transport means whereby the wafers housed in a wafer cassette are transported one by one successively to said metrology and each treating unit, and a transport chamber provided with a wafer cassette inlet for receiving a cassette containing sheets of wafer to be etched, in which said metrology, etching unit, ashing unit, wetting unit, drying unit and transport means are connected by a depressurizable transport passage.